Technical Datasheet

0.5mm Burn-in Socket

BOYD
TRUSTED INNOVATION

Platform Overview	FBGAxxx-051	CBGxx-A87	CBGxxx-A85	CBGxxx-081	CBGxxx-094
Socket Envelope (mm)	25 x 30 x 25.5	26 x 19.5 x 15.4	26 x 20 x 15.4	30 x 30 x 18.1	40 x 40 x 19.6
Package Array (max)	26 x 26	10 x 10	19 x 13	19 x 19	29 x 29
Package size (max)	14 x 14	17 x 11	11 x 10	10 x 10	15 x 15
Solder Ball Pb	•	•	•	•	•
Solder Ball Pb free	•	•	•	•	•
Interface BGA	•	•	•	•	•
Interface LGA	•		•	•	•
Current Rating	0.25A/pin @ 125°C				
Contact Force	Varied based on Pb or Pb-free solder balls (10-20 g/pin)				
Actuation Force	1.2 kg to 5 kg	1 kg (typ)	1.2 kg to 5 kg		
Pkg. Insertion Force	Zero Insertion Force				
Inductance	Approx. 6nH @ 50 MHz				
Contact Resistance	Initial: 150 mΩ (max) @10mA		10K cycles: 1Ω (max) @ 10mA		
Insulation Resistance	1000 mΩ @ 500 VDC				
Dielectric Withstand Voltage	For 1 minute @ 500 VAC	For 1 minute @ 700 VAC	For 1 minute @ 500 VAC		
Temperature	-55°C to 150°C				

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Product Description

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